

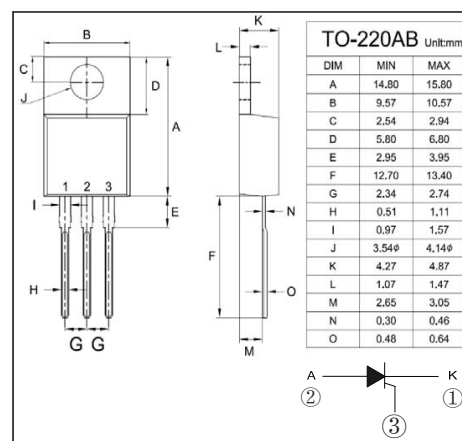
TO-220AB Silicon Controlled Rectifier

FEATURES

- Glass-passivated mesa chip for reliability and uniform
- Low on-state voltage and High ITSM
- RoHS products

MECHANICAL DATA

- Case: TO-220AB
- Mounting position: Any



MAXIMUM RATINGS AND CHARACTERISTICS

@ 25°C Ambient Temperature (unless otherwise noted) Single phase, half wave, 60 Hz, resistive or inductive load.
For capacitive load, derate by 20%.

PARAMETER		SYMBOL	RATINGS	UNIT
Repetitive Peak Off-State Voltages	BT151(F)-500R	V_{DRM}, V_{RRM}	500 (Note 2)	V
	BT151(F)-650R		650 (Note 2)	
	BT151(F)-800R		800	
Average On-State Current (half sine wave; $T_{mb} \leq 109^{\circ}C$)		$I_{T(AV)}$	7.5	A
RMS on-State Current (all conduction angles)		$I_{T(RMS)}$	12	A
Non-Repetitive Peak On-State Current (half sine wave; $T_J = 25^{\circ}C$ prior to surge)	$t = 10\text{ ms}$	I_{TSM}	100	A
	$t = 8.3\text{ ms}$		110	
I^2t for Fusing ($t = \square\text{ ms}$)		I^2t	50	A^2s
Repetitive Rate of Rise of On-State Current After Triggering ($I_{TM} = 20\text{ A}$; $I_G = 50\text{ mA}$; $dI_G/dt = 50\text{ mA}/\mu s$)		dI_T/dt	50	$A/\mu s$
Peak Gate Current		I_{GM}	2	A
Peak Gate Voltage		V_{GM}	5	V
Peak Reverse Gate Voltage		V_{RGM}	5	V
Peak Gate Power		P_{GM}	5	W
Average Gate Power (Over any 20 ms period)		$P_{G(AV)}$	0.5	W
Operating Junction Temperature		T_J	125	$^{\circ}C$
Storage Temperature		T_{STG}	-40 ~ +150	$^{\circ}C$
Junction to Mounting Base		θ_{JMb}	1.3	K/W
Junction to Ambient		θ_{JA}	60	K/W

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
2. Although not recommended, off-state voltages up to 800V may be applied without damage, but the thyristor may switch to the on-state. The rate of rise of current should not exceed 15A/ μs .

TO-220AB Silicon Controlled Rectifier
STATIC CHARACTERISTICS ($T_J = 25^\circ\text{C}$, unless otherwise stated)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNIT
Gate Trigger Current	I_{GT}	$V_D=12\text{ V}, I_T = 0.1\text{ A}$		4.2	15	mA
Latching Current	I_L	$V_D=12\text{ V}, I_{GT} = 0.1\text{ A}$		12.6	40	mA
Holding Current	I_H	$V_D=12\text{ V}, I_{GT} = 0.1\text{ A}$		12	20	mA
On-State Voltage	V_T	$I_T=23\text{ A}$		1.59	1.75	V
Gate Trigger Voltage	V_{GT}	$V_D = 12\text{ V}, I_T = 0.1\text{ A}$ $V_D = V_{DRM(max)}, I_T = 0.1\text{ A}, T_J = 125^\circ\text{C}$		0.7 0.5	1.5	V
Off-State Leakage Current	I_D, I_R	$V_D = V_{DRM(max)}, V_R = V_{RRM(max)}, T_J = 125^\circ\text{C}$		0.1	0.5	mA

DYNAMIC CHARACTERISTICS ($T_J = 25^\circ\text{C}$, unless otherwise stated)

PARAMETER	SYMBOL	CONDITIONS	MIN	MAX	UNIT	
Critical Rate of Rise of Off-State Voltage	dV_D/dt	$V_{DM} = 67\% V_{DRM(max)}, T_J = 125^\circ\text{C},$ exponential waveform	Gate open circuit	50	130	V/ μs
			$R_{GK} = 100\Omega$	200	1000	
Gate Controlled Turn-on Time	t_{GT}	$I_{TM} = 40\text{ A}, V_D = V_{DRM(max)}, I_G = 0.1\text{ A},$ $dI_G/dt = 5\text{ A}/\mu\text{s}$		2	μs	
Circuit Commutated Turn-off time	t_Q	$V_D = 67\% V_{DRM(max)}, T_J = 125^\circ\text{C};$ $I_{TM} = 20\text{ A}, V_R = 25\text{ V}, dI_{TM}/dt = 30\text{ A}/\mu\text{s},$ $dV_D/dt = 50\text{ V}/\mu\text{s}, R_{GK} = 100\ \Omega$		70	μs	

RATINGS AND CHARACTERISTIC CURVES

Fig 1. Maximum On-State Dissipation, P_{tot} , Versus Average On-State Current, $I_{T(AV)}$, Where a =form factor= $I_{T(RMS)}/I_{T(AV)}$

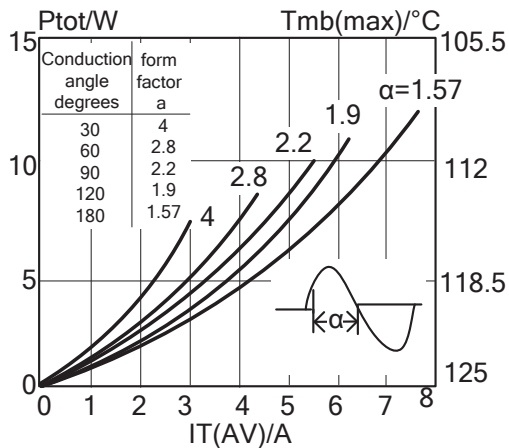


Fig 2. Maximum Permissible Non-Repetitive Peak On-State Current I_{TSM} , Versus Pulse Width tp for Sinusoidal Currents, $tp \leq 10ms$

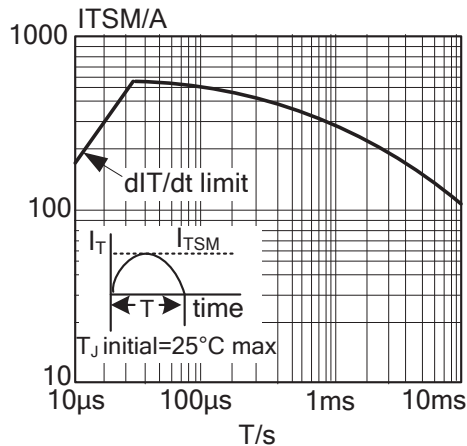


Fig 3. Maximum Permissible Rms Current $I_{T(RMS)}$, Versus Mounting Base Temperature T_{mb}

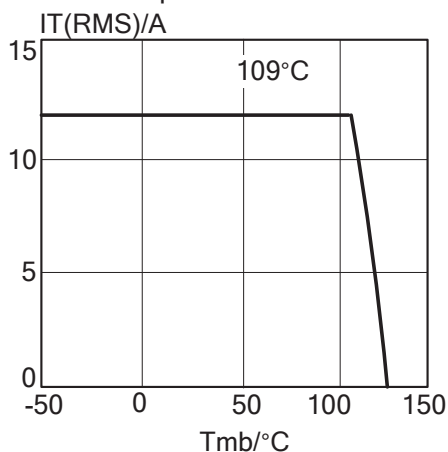


Fig 4. Maximum Permissible Non-Repetitive Peak On-State Current I_{TSM} , Versus Number Of Cycles, For Sinusoidal Currents, $f=50HZ$

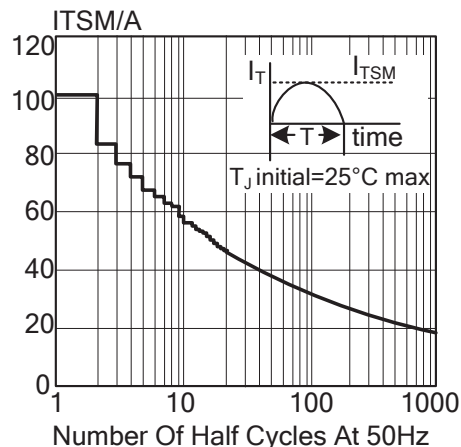


Fig 5. Maximum Permissible Repetitive Rms On-State Current $I_{T(RMS)}$, Versus Surge Duration, For Sinusoidal Currents, $f=50HZ$; $T_{mb} \leq 109^\circ C$

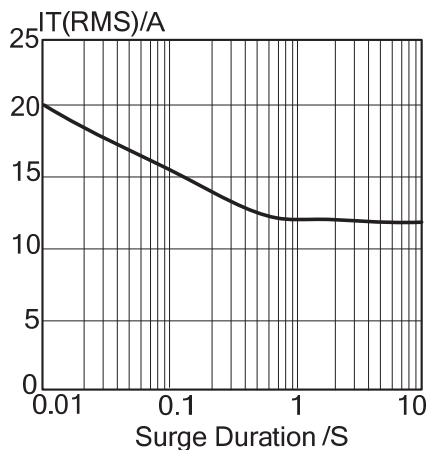
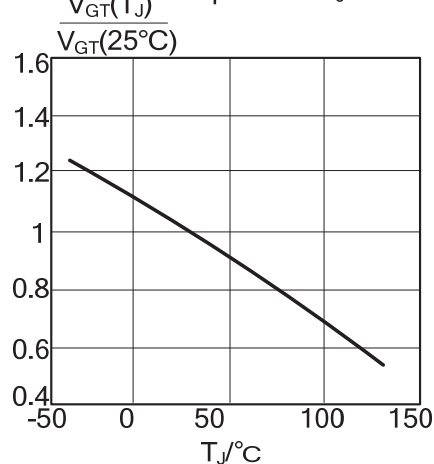


Fig 6. Normalised Gate Trigger Voltage $V_{GT}(T_J)/V_{GT}(25^\circ C)$, Versus Junction Temperature T_J



RATINGS AND CHARACTERISTIC CURVES

Fig 7. Normalised Gate Trigger Current $I_{GT}(T_J)/I_{GT}(25^\circ\text{C})$, Versus Junction Temperature T_J

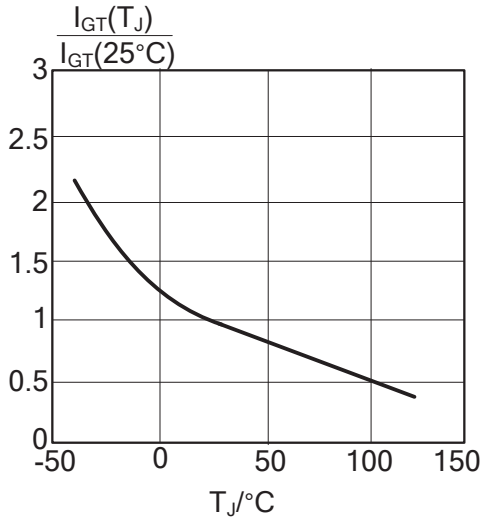


Fig 8. Normalised Latching Current $I_L(T_J)/I_L(25^\circ\text{C})$, Versus Junction Temperature T_J

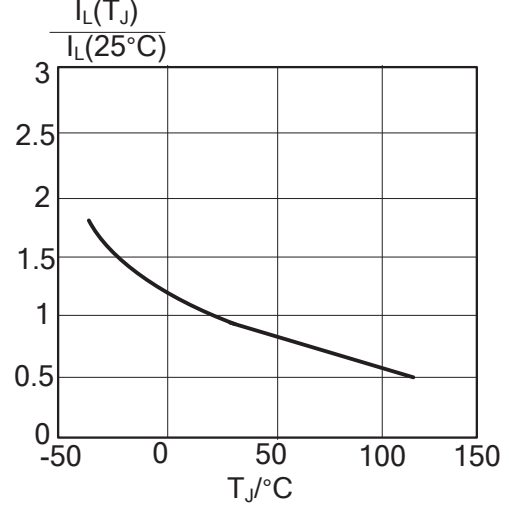


Fig 9. Normalised Holding Current $I_H(T_J)/I_H(25^\circ\text{C})$, Versus Junction Temperature T_J

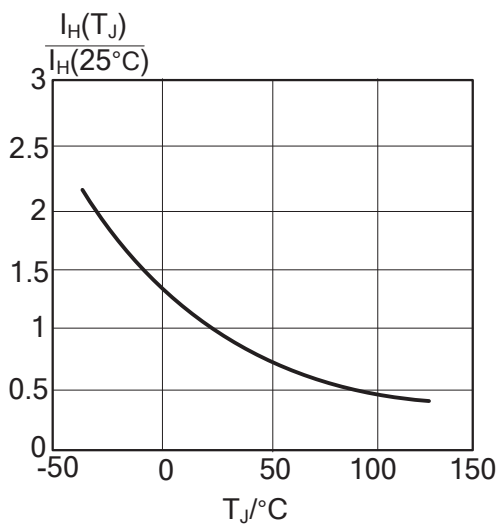


Fig 10. Typical and Maximum On-State Characteristic

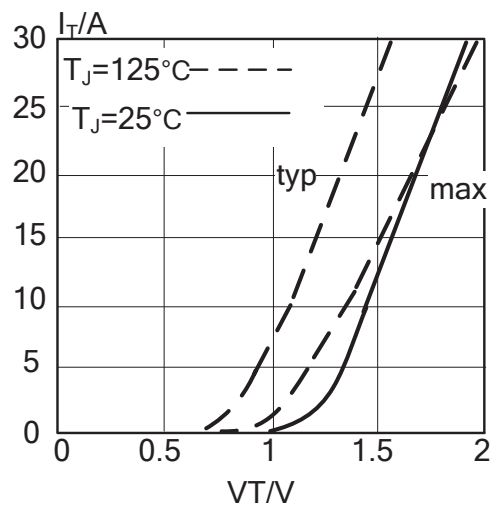


Fig 11. Transient Thermal Impedance Z_{thj-mb} , Versus Pulse Width t_p

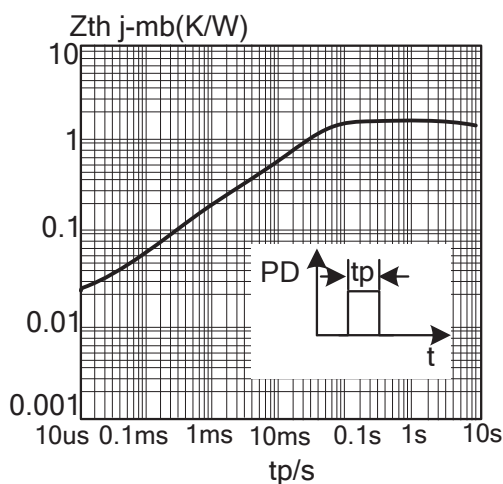


Fig 12. Typical, Critical Rate Of Rise Of Off-State Voltage, dV_D/dt Versus Junction Temperature T_J

